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**Call For Paper**

**The 7th International Conference on Communications, Signal Processing, and Systems (CSPS)**

（第七届通信、信号处理和系统（CSPS 2018）的国际会议）

第七届通信、信号处理和系统（CSPS 2018） 国际会议开始征稿。本会议由2012年开始，每年举办一届，在前六界会议中，论文集共发表了近2000篇学术论文，其中有280多篇扩充后投稿并发表到SCI期刊中。本次会议欢迎您的投稿，更多信息请扫描会议二维码或关注会议网站：http://[www.cspstjnu.com](http://www.cspstjnu.com)

**July 14-16 2018, Dalian, China**

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The7th International Conference on Communications, Signal Processing, and Systems (CSPS) will be held in July 2018 in Dalian, China. Prospective authors are invited to submit original technical papers for oral or poster presentations at CSPS and publication in the Conference Proceedings. The papers in communications, signal processing, and systems are solicited in the following topics, but are not limited to:

* Wireless communications
* Wireless networks
* Optical communications and networks
* Internet of Things
* Wireless sensor networks
* Wireless mesh networks
* Ad hoc networks
* Underwater sensor networks
* Network security
* Testbed of communications and networks
* Information theory and coding
* Multimedia communications
* Smart grid
* **Radar signal processing**
* Audio and acoustic signal processing
* Bio imaging and signal processing
* Design and implementation of signal processing systems
* Image, video and multidimensional signal processing
* Industry technology tracks
* Information forensics and security
* Machine learning for signal processing
* Multimedia signal processing
* Sensor array and multichannel signal processing
* Signal processing education
* Signal processing for communications and networking
* Signal processing theory and methods
* Speech processing
* Spoken language processing
* Analog Signal Processing
* Genomics Signal Processing
* Biomedical and Life-Science Circuits, Systems and Applications
* Circuits and Systems for Communications
* Computer-Aided Network Design
* Digital Signal Processing
* Education in Circuits and Systems
* Live Demonstrations of Circuits and Systems
* Multimedia Systems and Applications
* Nanoelectronics and Gigascale Systems
* Neural Networks and Systems
* Fuzzy Logic Systems
* Nonlinear Circuits and Systems
* Power and Energy Circuits and Systems
* Sensory Systems
* Radar Systems
* Chaos Systems
* Visual Signal Processing and Communications
* VLSI Systems and Applications
* Satellite and Space Communications

All accepted papers will be published in Lecture Notes in Electrical Engineering, a book series published by Springer, and is indexed by EI-indexed, ISI Proceedings, SCOPUS, MetaPress, Springerlink.

The 1st, 2nd, 3rd, 4th, 5th and 6th International Conference on Communications, Signal Processing, and Systems (CSPS) were held in Beijing in October 2012, in Tianjin in September 2013, in Hohhot in July 2014, in Chengdu in October 2015, in Chongqing in October 2016, in Harbin in July 2017 respectively. In the previous six conferences, more than 280 papers (after further extension) were selected into the following 10 SCI journals.

•EURASIP Journal on Wireless Communications and Networking

•Wiley Security and Communication Networks (SCN) Journal

•International Journal of Sensor Networks

•EURASIP Journal on Advances in Signal Processing

•(Elsevier) Physical Communications

•(Elsevier) Signal Processing

•(Elsevier) Ad Hoc Networks

•(Elsevier) Pattern Recognition

•Mobile Information Systems

•International Journal of Distributed Sensor Networks

It is expected that similar number of papers will be selected into SCI journals in 2018 CSPS conference.

**Submission:**

All submissions should be written in English with a maximum paper length of eight (8) printed pages including figures without incurring additional page charges.

Standard Springer book templates are available for both LaTeX and Microsoft Word format.

Please be aware that Springer book template size is much smaller than that of IEEE template (almost half size).

Only PDF files will be accepted for the review process and all submissions must be done through EDAS.

Authors can use the link below for submission:

<https://easychair.org/conferences/?conf=csps2018>

**Important Dates:**

**Paper Submission Deadline: April 20th, 2018**

**Acceptance Notification: June 15th, 2018**

**Camera Ready Paper: July 1st, 2018**

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